

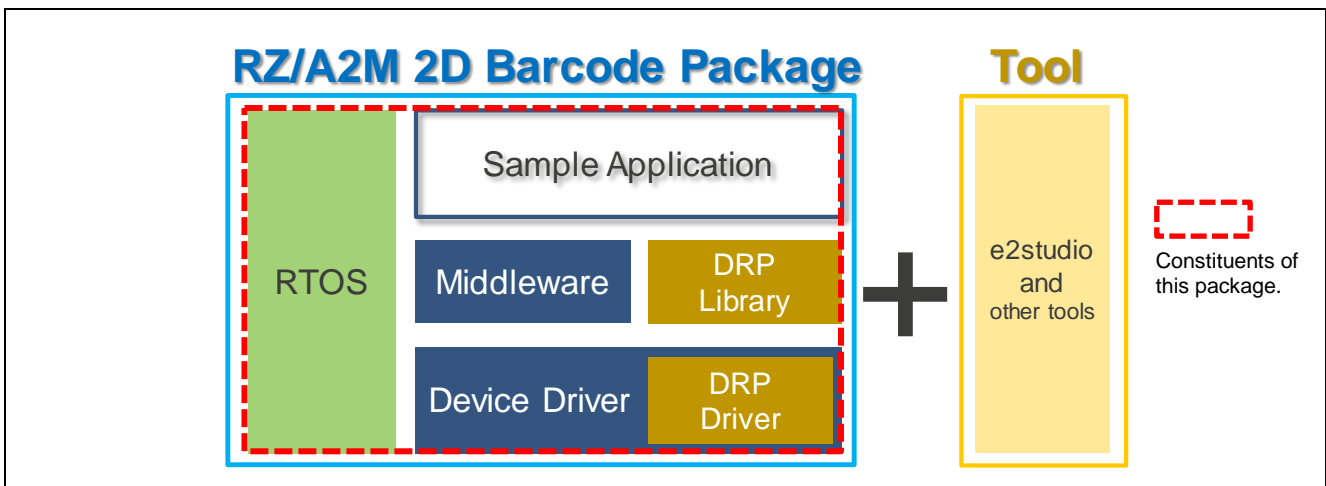
RZ/A2M Group

RZ/A2M 2D Barcode Package V1.03 Release Note

Introduction

This package contains 2D Barcode sample program for RZ/A2M. The 2D Barcode sample program executes detection and decoding of 2D Barcode using DRP (Dynamically Reconfigurable Processor) in RZ/A2M.

This package is one of RZ/A2M Software Package. RZ/A2M Software Package is a software development kit for the RZ/A2M that supports various RZ/A2M functions such as DRP, camera input, LCD output, and image adjustment. The 2D Barcode sample program includes each device driver, middleware, and sample application of RZ / A2M.



RZ/A2M 2D Barcode Package Configuration

For RZ/A2M Software Package details, refer following URL:

<https://www.renesas.com/us/en/products/software-tools/software-os-middleware-driver/software-package/rza2-software-development-kit-free-rtos.html>

If you want to add software that is not included in the sample program, copy source code from “RZ/A2M Software Core Package (R01AN4775)” (described in session 5).

Target Device / Target Board

Target Device: RZ/A2M

Target Board Kit: RZ/A2M Evaluation Board Kit (RTK7921053S00000BE)

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1. Package Contents

- Software

| No | Name | Ver. | Folder |
|----|---------------------------|------|-------------------|
| 1 | 2D Barcode Sample program | 1.10 | 2d_barcode_sample |
| 2 | DRP Driver | 0.91 | r_drp |
| 3 | DRP Library | - | drp_lib |

- DRP Library

| No | Name | Ver. |
|----|--|------|
| 1 | Affine | 0.90 |
| 2 | ARGB to Grayscale | 0.90 |
| 3 | Bayer to Grayscale | 0.91 |
| 4 | Bayer to RGB | 0.90 |
| 5 | Bayer to RGB Color Correction | 0.90 |
| 6 | Binarization (Adaptive) | 0.90 |
| 7 | Binarization (Adaptive/Bit output version) | 0.90 |
| 8 | Binarization (Fixed) | 0.90 |
| 9 | Canny Calculate | 0.90 |
| 10 | Canny Hysteresis | 0.90 |
| 11 | Circle fitting | 0.90 |
| 12 | Corner Harris | 0.90 |
| 13 | Cropping | 0.90 |
| 14 | Cropping RGB | 0.90 |
| 15 | Dilate | 0.90 |
| 16 | Erode | 0.90 |
| 17 | Find Contours | 0.90 |
| 18 | Gamma correction | 0.90 |
| 19 | Gaussian filter | 0.90 |
| 20 | Histogram | 0.90 |
| 21 | Histogram Normalization | 0.90 |
| 22 | Histogram Normalization RGB | 0.90 |
| 23 | Image rotate | 0.90 |
| 24 | Laplacian filter | 0.90 |
| 25 | Median filter | 0.90 |
| 26 | Minutiae delete | 0.90 |
| 27 | Minutiae extract | 0.90 |
| 28 | Prewitt filter | 0.90 |
| 29 | Reed-Solomon | 0.91 |
| 30 | Reed-Solomon (Gf8) | 0.91 |
| 31 | Resize bilinear | 0.91 |
| 32 | Resize bilinear fixed | 0.91 |
| 33 | Resize bilinear fixed RGB | 0.90 |
| 34 | Resize nearest | 0.90 |
| 35 | Simple ISP | 0.91 |
| 36 | Sobel filter | 0.90 |
| 37 | Thinning | 0.90 |
| 38 | Unsharp masking | 0.90 |

● Documents

| No | Title | Rev. | File |
|----|---|------|--|
| 1 | RZ/A2M Group RZ/A2M 2D Barcode Package V1.03 Release Note | 1.03 | (English) r01an4487ej0103-rza2m.pdf (This document) (Japanese) r01an4487jj0103-rza2m.pdf |
| 2 | RZ/A2M Group 2D Barcode Application Note | 1.10 | (English) r01an4503ej0110-rza2m.pdf (Japanese) r01an4503jj0110-rza2m.pdf |
| 3 | RZ/A2M Group DRP Driver User's Manual | 1.01 | (English) r01us0355ej0101-rza2m.pdf (Japanese) r01us0355jj0101-rza2m.pdf |
| 4 | RZ/A2M Group DRP Library User's Manual | 1.03 | (English) r01us0367ej0103-rza2m.pdf (Japanese) r01us0367jj0103-rza2m.pdf |
| 5 | RZ/A2M Group RZ/A2M Software Package Quick Start Guide | 1.02 | (English) r01qs0027ej0102-rza2m.pdf (Japanese) r01qs0027jj0102-rza2m.pdf |

● Folder structure of 2D Barcode Package

| | |
|--|--|
| r01an4487xx0103-rza2-swpkg | : top folder |
| ├─rza2m_2d_barcode_sample_freertos_gcc.zip | : RZ/A2M Group 2D Barcode sample program |
| ├─r01an4487ej0103-rza2m.pdf | : RZ/A2M Group 2D Barcode Package Release Note (English) |
| ├─r01an4487jj0103-rza2m.pdf | : RZ/A2M Group 2D Barcode Package Release Note (this document) |
| ├─r01qs0027ej0102-rza2m.pdf | : RZ/A2M Group Software Package Quick Start Guide (English) |
| └─r01qs0027jj0102-rza2m.pdf | : RZ/A2M Group Software Package Quick Start Guide (Japanese) |

- Folder structure of 2D Barcode Sample Program

| rza2m_2d_barcode_sample_freertos_gcc.zip : Project Top Folder | |
|---|--|
| ├─ demos | |
| ├─ renesas | |
| ├─ rza2m-ebk | |
| ├─ common | |
| ├─ applicaton_code | : main.c |
| ├─ config_files | : Configurations |
| ├─ e2studio | |
| ├─ .settings | : Project Setting Files |
| ├─ bootloader | : QSPI boot loader |
| ├─ doc | : Document of this sample application |
| ├─ r01an4503ej0110-rza2m.pdf | : RZ/A2M Group 2D Barcode Application Note (English) |
| ├─ r01an4503jj0110-rza2m.pdf | : RZ/A2M Group 2D Barcode Application Note (Japanese) |
| ├─ generate | : Source files generated / configured by Smart Configurator |
| ├─ compiler | : Source files depended on the compiler |
| ├─ configuration | : Header files for project configuration |
| ├─ drivers | : Basic drivers |
| ├─ r_cache | : Cache driver |
| ├─ doc | : Document of Cache driver |
| ├─ inc | : Header files for Cache driver |
| ├─ src | : Source files for Cache driver |
| ├─ r_cpg | : Clock pulse generator driver (same folder structure as Cache driver) |
| ├─ r_gpio | : GPIO driver (same folder structure as Cache driver) |
| ├─ r_intc | : INTC driver (same folder structure as Cache driver) |
| ├─ r_mmu | : MMU driver (same folder structure as Cache driver) |
| ├─ r_stb | : STB driver (same folder structure as Cache driver) |
| ├─ os_abstraction | : OS abstraction layer (same folder structure as Cache driver) |
| ├─ doc | : Document of OS abstraction layer |
| ├─ inc | : Header files for OS abstraction layer |
| ├─ src | : Source files for OS abstraction layer |
| ├─ sc_drivers | : General drivers |
| ├─ r_cbuffer | : Ring buffer (same folder structure as DRP driver) |
| ├─ r_ceu | : CEU driver (same folder structure as DRP driver) |
| ├─ r_drp | : DRP driver (same folder structure as DRP driver) |
| ├─ doc | : Documents of DRP driver |
| ├─ r01us0355ej0101-rza2m.pdf | : RZ/A2M Group DRP Driver User's Manual (R01US0355) (English) |
| ├─ r01us0355jj0101-rza2m.pdf | : RZ/A2M Group DRP Driver User's Manual (R01US0355) (Japanese) |
| ├─ r01us0367ej0103-rza2m.pdf | : RZ/A2M Group DRP Library User's Manual (R01US0367) (English) |
| ├─ r01us0367jj0103-rza2m.pdf | : RZ/A2M Group DRP Library User's Manual (R01US0367) (Japanese) |
| ├─ drp_lib | : Source files for DRP library |
| ├─ inc | : Header files for DRP driver |
| ├─ src | : Source files for DRP driver |
| ├─ r_mipi | : MIPI driver (same folder structure as DRP driver) |
| ├─ r_ostm | : OS timer driver (same folder structure as DRP driver) |
| ├─ r_riic | : I2C driver (same folder structure as DRP driver) |
| ├─ r_nvapi | : Video utility (same folder structure as DRP driver) |
| ├─ r_scifa | : SCIFA driver (same folder structure as DRP driver) |
| ├─ r_vdc | : VDC driver (same folder structure as DRP driver) |
| ├─ system | : System files for example, IO registers |
| ├─ src | : Source files for application |
| ├─ renesas | : Software developed by Renesas |
| ├─ application | : pplication source files developed by Renesas |
| ├─ zxing_lib | : Source files for ZXing library |
| ├─ bigint | : Source files for integer operation |
| ├─ zxing | : Source files of ZXing |
| ├─ lib | |
| ├─ FreeRTOS | : FreeRTOS™ |
| ├─ include | : FreeRTOS™ header files |
| ├─ third_party | |
| ├─ mcu_vendor | |
| ├─ renesas_rz | |
| ├─ amazon_freertos_common | : RZ/A2MCommon Settings |
| ├─ LICENSE | |

2. System Requirements

The system requirements for this sample program are listed below.

| Item | Description |
|------------------------------------|--|
| CPU | RZ/A2M (R7S921051VCBG, R7S921052VCBG, R7S921053VCBG) |
| Board | RZ/A2M CPU board (RTK7921053C00000BE) RZ/A2M SUB board (RTK79210XXB00000BE) RZ/A2M Display Output Board (RTK79210XXB00010BE) |
| Compiler | GNU Arm Embedded Toolchain 6-2017-q2-update |
| Integrated development environment | e2 studio Version 7.4.0. |
| Emulator | SEGGER J-Link Base |
| Camera | Raspberry Pi Camera V2 |
| Monitor | Monitor compatible with Full-WXGA(1366*768) resolution |

3. Operation Confirmation Conditions

(1) Boot mode

Boot mode 3

(Boot from serial flash memory 3.3V)

* The program cannot be operated if the boot mode except the above is specified.

(2) Operating frequency

The RZ/A2M clock pulse oscillator is set to see that the RZ/A2M clocks on the CPU board have the following frequencies.

(The frequencies indicate the values in the state that the clock with 24MHz is input to the EXTAL pin in RZ/A2M clock mode 1.)

| | |
|------------------------------------|----------|
| - CPU clock (I clock) | : 528MHz |
| - Image processing clock (G clock) | : 264MHz |
| - Internal bus clock (B clock) | : 132MHz |
| - Peripheral clock1 (P1 clock) | : 66MHz |
| - Peripheral clock0 (P0 clock) | : 33MHz |
| - QSPI0_SPCLK | : 66MHz |
| - CKIO | : 132MHz |

(3) Serial flash memory used

Manufacturer : Macronix Inc.

Product No. : MX25L51245G

(4) Setting for cache

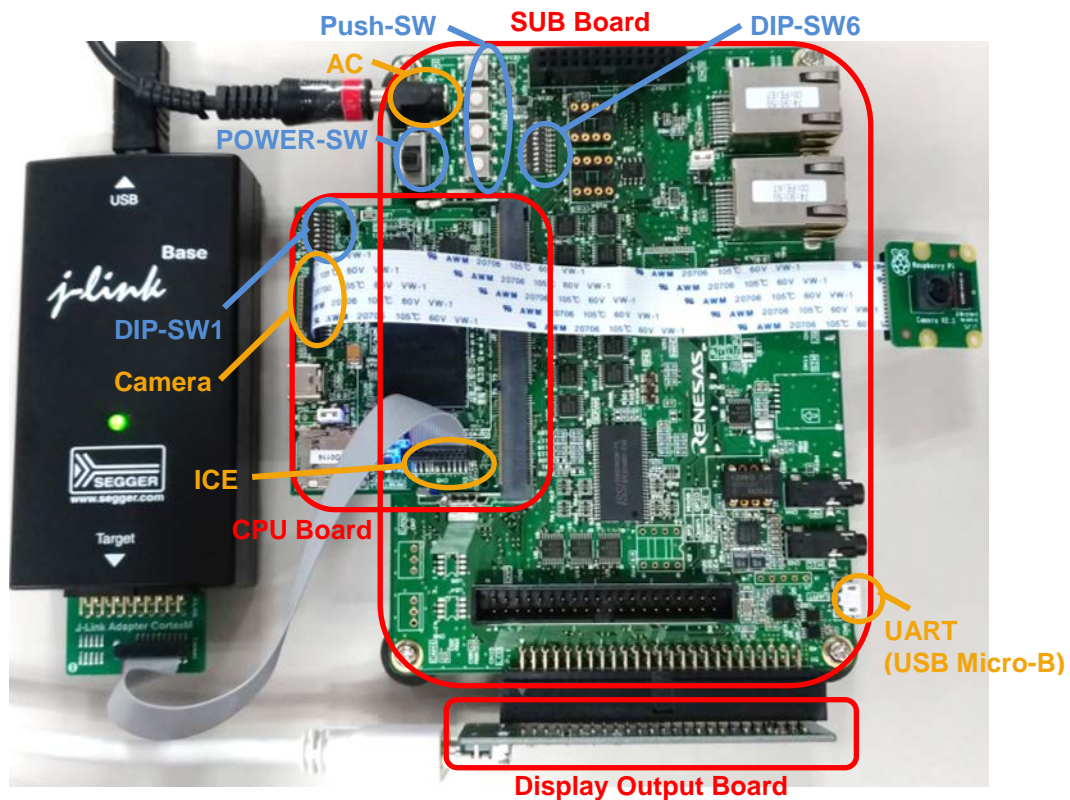
Refer to the "RZ/A2M group Example of Initialization" application note(R01AN4321) about "Setting for MMU" included in "RZ/A2M Software Core Package (R01AN4775)" for the valid/invalid area of L1 and L2 caches.

4. Operation procedure

4.1 Hardware preparation

Connect the hardware described in “2 System Requirements” as follows.

- (1) Connect the CPU board and the SUB board.
- (2) Connect the SUB board and Display Output Board.
- (3) Connect the MIPI camera to the CPU board.
- (4) Connect the J-Link Base to the CPU board.
- (5) Connect the SUB board and the AC Adapter.



To operate this package, set the DIP-SW and jumpers as follows.

Refer to the CPU board and the SUB board user's manual (R20UT4239, R20UT4240) for more details about setting for the DIP switches and jumpers.

Set the DIP switches and jumpers of the CPU board as follows.

| DIP-SW1 | | | | | | | |
|---------|-----|----|-----|-----|----|----|----|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 |
| ON | OFF | ON | OFF | OFF | ON | ON | ON |

| JP | Configuration | Function |
|-----|---------------|--|
| JP1 | 1-2 | Setting to supply 3.3V power for PVcc_SPI of RZ/A2M and U2 |
| JP2 | 2-3 | Setting to supply 1.8V power for PVcc_HO of RZ/A2M and U3 |
| JP3 | Open | Use USB ch 0 in the function mode (Not supply VBUS0 power) |

Set the DIP switches and jumpers of the SUB board as follows.

| DIP-SW2 | | | | | | | | | |
|---------|-----|-----|----|----|----|----|-----|-----|-----|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 |
| OFF | OFF | OFF | ON | ON | ON | ON | OFF | OFF | OFF |

| JP | Configuration | Function |
|-----|---------------|---|
| JP1 | 2-JP2 | Setting to use PJ_1 as interrupt terminal for IRQ0 switch (SW3) |

4.2 How to build source code

Refer to the RZ/A2M Group RZ/A2M Software Package Quick Start Guide (R01QS0027) included in this package for the procedure of building, downloading and executing the sample program.

5. Reference Application Notes

Following is the list of application notes related to this software package.

RZ/A2M Group RZ/A2M Software Core Package (R01AN4775).

Drivers and middleware for RZ/A2M that can be added to the project bundled in this package.

6. Restrictions

The Restrictions of this package are shown as follow.

Table 6-1 Restrictions

| No. | Type | Description |
|-----|--------------|--|
| 1 | DRP Driver* | The following API Functions are not supported. - R_DK2_Uninitialize - R_DK2_Inactivate - R_DK2_GetInfo If these functions are called, these functions occur an error and return "R_DK2_ERR_INTERNAL". |
| 2 | DRP Driver * | The function that load the configuration data in background is not supported. This function validates when argument "pload" of R_DK2_Load Function is set to anything other than NULL. In the version in this package this function occurs an error and return "R_DK2_ERR_INTERNAL". |
| 3 | DRP Driver * | R_DK2_Load Function notifies the return value "R_DK2_ERR_DEVICE", when detects a transfer error of the configuration data. In the version in this package this function is not supported. |
| 4 | DRP Driver * | Processing Completion Callback Function notifies the argument "result" is "R_DK2_ERR_DEVICE", when detects a transfer error in DRP. In the version in this package this function is not supported. |
| 5 | DRP Driver * | Processing Completion Callback Function notifies the argument "result" is "R_DK2_ERR_DEVICE", when detects a transfer stopped by calling R_DK2_Unload Function of R_DK2_Inactivate Function. In the version in this package this function is not supported. |

Note 1 Please refer to "RZ/A2M Group DRP Driver User's Manual(R01US0355)" for details of DRP Driver's function.

7. Precautions

The Precautions of this package are shown as follow.

Table 7-1 Precautions

| No. | Type | Description |
|-----|--------------|---|
| 1 | Ethernet | It is not possible to add the TCP/IP protocol stack to a project by using Smart Configurator. In the case you use the TCP/IP protocol stack, please use "Ethernet sample program" bundled in "RZ/A2M Simple Applications Package"(R01AN4494). |
| 2 | Environment | If it is happened a build error while building the project of this package as it is, the setting of environment may be incorrect. Check following items: · Follow section 3 of "RZ/A2M Software Package Quick Start Guide"(R01QS0027) · Install e2 studio v7.3 or later again. |
| 3 | Environment | To avoid build error, expand the project to the folder with short full-path. |
| 4 | Environment | To avoid build error, expand the project to the folder without multi-byte character. |
| 5 | Environment | This package includes elf-formatted boot loader. Therefore, the project to generate the boot loader is not bundled. Following application note includes the boot loader project. To get it, please download from Renesas site: RZ/A1LU Group Example of Booting from Serial Flash Memory (R01AN4333) |
| 6 | All | The folder location of following drivers has moved to "generate\sc_drivers"(V1.01) from "src\renesas\drivers"(V1.00). r_ceu, r_drp, r_mipi, r_riic, r_rvapi and r_vdc Therefore, they are incompatible with the project between V1.01 and V1.00. |
| 7 | All | Since V1.03, the folder structure of the project using FreeRTOS has been changed to follow Amazon FreeRTOS. Therefore, they are incompatible with the project between V1.03 and V1.02. |
| 8 | TES Guiliani | It is not possible to add TES Guiliani to an existing project. When using TES Guiliani, please use Guiliani 2.2 SDK for RZ/A2M Software Package as a base project. |
| 9 | TES Guiliani | Contact following URL if you use both TES Guiliani and TCP/IP protocol stack. https://www.renesas.com/support/contact.html |

Appendix

- Function overview of DRP Library

| Category | Function | Processing content |
|---------------------------------|------------------------------------|--|
| Image processing | Simple ISP | ISP (Image Signal Processor) which is optimal for image recognition. Perform color component integration, color component correction, demosaicing, noise elimination, sharpening, and gamma correction for RAW data (Bayer array) from CMOS. |
| Color conversion | Bayer to Grayscale | Converts from RAW data acquired from CMOS to grayscale. |
| | Bayer to RGB | Converts from RAW data acquired from CMOS to RGB. |
| | Bayer to RGB with color correction | Converts from RAW data acquired from CMOS to RGB and color correction. |
| | ARGB to Grayscale | Converts from ARGB to grayscale. |
| | Binarization(Fixed) | Converts the image to a binary image with a fixed threshold. |
| | Binarization(Adaptive) | Converts the image to a binary image with a dynamic threshold matching the surrounding image. |
| Image filtering | Median filter | Reduces the noise contained in the image. |
| | Gaussian filter | The image smoothing. |
| | Unsharp masking | The image sharpening. |
| | Gamma correction | Corrects the image with gamma value. |
| Geometric Image Transformations | Cropping | Crops a part of the image. |
| | Resize | Resizes the image. (There are 2 kind of libraries, Bilinear and Nearest.) |
| | Image Rotate | Rotates the image. |
| | Affine | Performs parallel translation and linear transformation of the image. |
| Feature detection | Canny edge detection | Detects the edge of the image using the Canny method. |
| | Corner Harris detection | Detects the corner contained in the image using the method devised by Chris Harris. |
| | Sobel filter | Creates the edge of the image using Sobel filter. |
| | Prewitt filter | Creates the edge of the image using Prewitt filter. |
| | Laplacian filter | Creates the edge of the image using Laplacian filter. |
| | Thinning | Performs thinning of the image. |
| | Minutiae extraction | Process of extracting feature points of fingerprint ridges used in fingerprint recognition. |
| | Circle fitting | Detects circle from the input image. |
| | Histogram | Generates a histogram from the input image. |
| | Histogram normalization | Generates a histogram from the input image and normalize the input image. |
| | Find Contours | Detect a contour and output its circumscribed rectangle. |
| Morphological Transformation | Dilate | Dilation of white part in the image. |
| | Erode | Erosion of white part in the image. |
| | Opening *1 | Dilation after erosion. Noise in the white part is reduced. |
| | Closing *1 | Erosion after dilation. Noise in the black part is reduced. |
| Other | Reed-Solomon | Error correction using Reed-Solomon code. |

Note 1 This function can be executed by a combination of Dilate and Erode.

Currently under development. It is subject to change without notice.

Please refer to "RZ/A2M Group DRP Library User's Manual(R01US0367)" for details of DRP Library's function.

- Performance list of DRP Library

| Category | Function | Tiles | Processing performance [ms] | | | Note |
|--------------------------|--------------------------------|-------|-----------------------------|--------|--------|---------------------------------------|
| | | | DRP | CPU | vs CPU | |
| Image processing | Simple ISP(Bayer to Color) | 6 | 11.49 | - | - | |
| | | 3 | 23.02 | - | - | |
| | Simple ISP(Bayer to Grayscale) | 6 | 6.68 | - | - | |
| | | 3 | 13.13 | - | - | |
| Color conversion | Bayer to Grayscale | 1 | 0.85 | 15.3 | x 18.0 | 6 Parallel Processing |
| | Bayer to RGB | 2 | 2.85 | 8.9 | x 3.1 | 3 Parallel Processing |
| | ARGB to Grayscale | 1 | 0.61 | 5.9 | x 9.7 | 6 Parallel Processing |
| | Binarization(Fixed) | 1 | 0.18 | 2.3 | x 12.8 | 6 Parallel Processing |
| | Binarization(Adaptive) | 3 | 1.69 | 10.1 | x 6.0 | |
| Image filtering | Median filter | 1 | 0.85 | 76.1 | x 89.5 | 6 Parallel Processing |
| | Gaussian filter | 1 | 0.85 | 14.4 | x 16.9 | 6 Parallel Processing |
| | Unsharp masking | 2 | 1.67 | 34.1 | x 20.4 | 3 Parallel Processing |
| | Gamma correction | 1 | 0.23 | 3.8 | x 16.5 | 6 Parallel Processing |
| Geometric transformation | Cropping | 1 | 0.06 | 0.2 | x 3.3 | 6 Parallel Processing |
| | Resize Bilinear Fixed | 4 | 2.24 | 2.7 | x 1.2 | |
| | Resize Bilinear | 6 | 1.29 | 3.1 | x 2.4 | |
| | Resize Nearest | 6 | 0.33 | 0.6 | x 1.9 | |
| | Image Rotate | 1 | 0.34 | 3.0 | x 8.7 | 6 Parallel Processing |
| | Affine | 6 | 25.86 | 41.6 | x 1.6 | |
| Feature detection | Canny edge detection | 1+2+6 | 10.59 | 110.6 | x 10.4 | Parallel Processing & Dynamic Loading |
| | Harris corner detection | 1+6 | 11.64 | 235.3 | x 20.2 | Parallel Processing & Dynamic Loading |
| | Sobel filter | 1 | 0.85 | 30.7 | x 36.1 | 6 Parallel Processing |
| | Prewitt filter | 1 | 0.80 | 30.7 | x 38.4 | 6 Parallel Processing |
| | Laplacian filter | 1 | 0.81 | 29.1 | x 36.0 | 6 Parallel Processing |
| | Circle Fitting | 2 | 97.80 | 1135.0 | x 11.6 | |
| | Minutiae Extract | 3 | 0.81 | - | - | 2 Parallel Processing |
| | Minutiae Delete | 2 | 0.36 | - | - | |
| Morphological operations | Thinning | 3 | 0.54 | - | - | 2 Parallel Processing |
| | Dilate | 1 | 0.85 | 18.0 | x 21.2 | 6 Parallel Processing |
| Other | Erode | 1 | 0.85 | 18.0 | x 21.2 | 6 Parallel Processing |
| | Reed-Solomon | 1 | 0.24 | 5.0 | x 20.8 | 6 Parallel Processing |
| | Histogram | 2 | 1.82 | 3.5 | x 1.9 | |

Note Currently under development. Performance data may change.

| | |
|-------------|---|
| Image size | 640 x 480 VGA |
| Image color | Grayscale 8BPP Simple ISP (Bayer to Color) : YUV422 Bayer to RGB : RGB888 |
| CPU | RZ/A2M Cortex®-A9@528MHz |
| RAM | RZ/A2M internal RAM |
| ROM | QSPI Flash-ROM |

Revision History

| Rev. | Date | Description | |
|------|---------------|-------------|--|
| | | Page | Summary |
| 1.00 | Sep. 28, 2018 | - | First Edition issued |
| 1.01 | Dec. 28, 2018 | 3, 4 | Updated DRP Driver to Ver.0.91. Added the following to DRP Library. (1) CircleFitting (2) Histogram (3) Prewitt (4) ResizeBilinearFixed (5) Simplelsp |
| | | 4 | Updated the RZ/A2M Group DRP Library User's Manual. |
| | | 5 | Added 2 System Requirements. |
| | | 6 | Added 3 Operation Confirmation Conditions. |
| | | 7 | Added 4 Operation Procedure. |
| | | 10 | Updated function overview of DRP Library. |
| | | 11 | Updated Performance list of DRP Library. |
| 1.02 | Apr. 15, 2019 | 3, 4 | Updated the 2D Barcode sample program to Ver.1.01. Added the following to DRP Library. (1) Affine (2) Bayer2Rgb (3) ImageRotate (4) Laplacian (5) MinutiaeDelete (6) MinutiaeExtract (7) ReedSolomonGf8 (8) Thinning Version up the following to DRP Library. (1) Simplelsp |
| | | 4 | Updated the RZ/A2M Group 2D Barcode Application Note. Updated the RZ/A2M Group DRP Library User's Manual. |
| | | 11 | Updated function overview of DRP Library. |
| | | 12 | Updated Performance list of DRP Library. |
| 1.03 | Jun. 07,2019 | 3 | Updated the 2D Barcode sample program to Ver.1.10. Added the following to DRP Library. (1) Bayer to RGB Color Correction (2) Cropping RGB (3) Find Contours (4) Histogram Normalization (5) Histogram Normalization RGB (6) Resize bilinear fixed RGB |
| | | 4 | 1 Package Contents Update each document name to latest version Update Folder structure to latest version |
| | | 5 | 2 System Requirements Update the version of e2 studio |
| | | 11 | Table 7-1 Precautions Update the version of e2 studio |
| | | 12 | Updated function overview of DRP Library. |

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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